

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L4	528	257/522.ccls. 438/411.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2008/03/11 16:42
L5	12599	257/347.ccls. 257/415.ccls. 257/419.ccls. 257/506.ccls. 257/510.ccls. 257/522.ccls. 257/524.ccls. 257/ e21.564.ccls. 257/ e29.324.ccls. 438/53.ccls. 438/404.ccls. 438/411.ccls. 438/424.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2008/03/11 16:49
L6	349	L5 and (((silicon si) near2 (film layer)) same (substrate wafer fragment support \$6) same (pillar column anchor\$6 post))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/11 16:49
L7	218	((silicon si epitax \$8) near2 (film layer)) and (substrate wafer fragment support \$6) and (pillar column anchor\$6 post) and (((component element electrode contact terminal) with (fix\$6 mechanical\$6 connect\$6))	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/11 17:02

L8	166	((silicon si epitax \$8) near2 (film layer)) with (pillar column anchor\$6 post)) same (substrate wafer fragment support \$6) same ((component element electrode contact terminal) near4 (fix\$6 mechanical\$6 connect\$6))	US-PGPUB; USPAT	OR	ON	2008/03/11 17:11
L9	63	((soi sos) not "so") (silicon near (insulator sapphire))) and (body near (tie tied tying contact)) and ((component element electrode contact terminal) with (fix\$6 mechanical\$6 connect\$6))	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/11 17:14
L10	55	((soi sos) not "so") (silicon near (insulator sapphire))) same (body near (tie tied tying contact)) same ((component element electrode contact terminal) with (fix\$6 mechanical\$6 connect\$6))	US-PGPUB; USPAT	OR	ON	2008/03/11 17:18

L11	12599	257/347.ccls. 257/415.ccls. 257/419.ccls. 257/506.ccls. 257/510.ccls. 257/522.ccls. 257/524.ccls. 257/ e21.564.ccls. 257/ e29.324.ccls. 438/53.ccls. 438/404.ccls. 438/411.ccls. 438/424.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2008/03/11 17:20
L12	74	L11 and (((soi sos) not "so") (silicon near (insulator sapphire))) same (body near (tie tied tying contact)))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/11 17:20
L13	74	(((soi sos) not "so") (silicon near (insulator sapphire))) same (substrate wafer fragment support \$6) same (pillar column anchor\$6 post) same (sti trench groov\$6 recess\$6)	US-PGPUB; USPAT	OR	ON	2008/03/11 17:25
L14	44	(((soi sos) not "so") (silicon near (insulator sapphire))) and (substrate wafer fragment support \$6) and (pillar column anchor\$6 post) and (sti trench groov\$6 recess\$6)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/11 17:27

L15	10	L11 and (((soi sos) not "so") (silicon near (insulator sapphire))) same (pillar column anchor\$6 post) same (sti trench groov\$6 recess \$6))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/11 17:33
L16	267	(((silicon si epitax \$8) near2 (film layer)) and (pillar column anchor\$6 post) and (substrate wafer fragment support \$6) and ((component element electrode contact terminal) near4 (fix\$6 mechanical\$6 connect\$6))).clm.	US-PGPUB	OR	ON	2008/03/11 17:36
L17	88	(((silicon si epitax \$8) near2 (film layer)) and (pillar column anchor\$6 post) and (substrate wafer fragment support \$6) and ((component element electrode contact terminal) near4 (fix\$6 mechanical\$6 connect\$6)) and (cap\$6 diaphragm barb\$6 undercut \$6)).clm.	US-PGPUB	OR	ON	2008/03/11 17:39

3/11/08 6:03:41 PM

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